NGAC P910-04   *Technical Bulletin*

Low Shrinkage and Controlled Flow Adhesive

Description:
NGAC P910-04 is a high viscosity, controlled flow encapsulant designed for microelectronics applications requiring low shrinkage and high reliability performance.

Advantages and Applications:
Uses include protecting wire bonds and bare die and other micro-electronic structural assembly applications. NGAC P910-04 has a low CTE resulting in low shrinkage upon cure and no stress to substrates. It is highly resistant to humidity and will withstand reflow temperatures up to 260C.

NGAC P910-04 features the following characteristics that enable ease of use.

Storage Requirements:
NGAC P910-04 is packaged in pre-mixed and frozen syringe. It must be shipped in dry ice* and stored in a freezer. The optimum storage temperature is -60˚C to -70˚C and the minimum storage temperature recommended is -57˚C.

*Temperature during shipment should be maintained at -40˚C or colder with dry ice.

Shelf life of each lot will be exactly 6 months from date of manufacture with storage at -57˚C minimum.

Properties	Typical Value	Test Method
Color	Black	Visual
Specific Gravity	1.80	ASTM-D1875
Hardness Shore D	95	ASTM-D2240
Glass Transition, T_g	130°C	ASTM-E1356
CTE, ppm/°C		ASTM-E831
Alpha1, -40 to 100°C	20	
Alpha2, 150 to 220°C	68	
Operating Temperature:	-40 to 260°C	TP-305
Working Life***	1.5-3h	TP-201

Cure Schedule:

Temperature	100°C	**PLUS**	150°C
Time	30 minutes		45 minutes

OR

Temperature	150°C
Time	45 minutes

***Working life is subjective to application requirements.

For additional information or assistance, please call
978-436-9600

All values reported above are typical values and are for reference use only. These values are not intended for use in developing specifications. Application testing under specific conditions should be performed to determine actual results and fitness for use.

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